

Advanced IC Packaging Market: Trends, Forecast and Competitive Analysis

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Abstracts

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Advanced IC Packaging Market Trends and Forecast

The future of the advanced IC packaging market looks promising with opportunities in the consumer & communication, automotive, industrial, healthcare, and aerospace & defense industries. The global advanced IC packaging market is expected to reach an estimated \$52.3 billion by 2027 with a CAGR of 5.7% from 2021 to 2027. The major drivers for this market are growing semiconductor industry, increasing miniaturization of electronic devices, demand for higher speed and smaller pitch size, and increasing penetration of 2.5D/3D packaging technology.

Emerging Trends in the Advanced IC Packaging Market

Emerging trends, which have a direct impact on the dynamics of the industry, include development of packaging solutions for AI and IoT and introduction of new IC packaging technologies, such as fan out and 2.5D/3D.

A total of 107 figures / charts and 68 tables are provided in this 205-page report to help in your business decisions. A sample figure with insights is shown below. To learn the scope of benefits, companies researched, and other details of the advanced IC packaging market report, please download the report brochure.

Advanced IC Packaging Market by Segment

The study includes a forecast for the global advanced IC packaging market by packaging type, end use industry, and region as follows:

Advanced IC Packaging Market by Packaging Type [Value (\$M) shipment analysis for 2016 – 2027]:

Flip-Chip

Fan-in Wafer Level (WLP) Packaging

Embedded-Die

Fan-Out

2.5D/3D

Advanced IC Packaging Market by End Use Industry [Value (\$M) shipment analysis for 2016 – 2027]:

Consumer and Communication

Automotive

Industrial

Healthcare

Aerospace and Defense

Others

Advanced IC Packaging Market by Region [Value (\$M) shipment analysis for 2016 – 2027]:

North America

Europe

Asia Pacific

The Rest of the World

List of Advanced IC Packaging Companies

Companies in the market compete on the basis of product quality offered. Major players in this market focus on expanding their manufacturing facilities, R&D investments, infrastructural development, and leverage integration opportunities across the value chain. With these strategies advanced IC packaging companies cater increasing demand, ensure competitive effectiveness, develop innovative products & technologies, reduce production costs, and expand their customer base. Some of the advanced IC packaging companies profiled in this report includes.

Amkor Technology

Taiwan Semiconductor

Advanced Semiconductor Engineering Technology

Intel Corporation

Samsung Electronics

JCET Group

Texas Instruments

Toshiba Corporation

Renesas

Advanced IC Packaging Market Insight

Lucintel forecasts that flip-chip will remain the largest segment due to rise in demand for high speed portable devices and high packaging density.

Consumer and communication will remain the largest end-use industry during the forecast period. Increasing demand for smartphones, connected and high performance consumer devices with AI technology, and demand for high performance computing are driving the demand for advanced IC packaging in the consumer and communication market.

Asia Pacific will remain the largest region over the forecast period due to the presence of large foundries and manufacturing hub for electronic devices. Economic growth, growing urbanization, growing disposable income, and increasing adoption of digital technologies, such as 5G, Internet of things (IoT), and artificial intelligence (AI) are driving the demand for advanced IC packaging market

Features of Advanced IC Packaging Market

Market Size Estimates: Advanced IC packaging market size estimation in terms of value (\$M)

Trend and Forecast Analysis: Market trends (2016-2021) and forecast (2022-2027) by various segments and regions.

Segmentation Analysis: Market size by packaging type and end use industry

Regional Analysis: Advanced IC packaging market breakdown by North America, Europe, Asia Pacific, and the Rest of the World.

Growth Opportunities: Analysis of growth opportunities in different packaging type, end use industry, and regions for the advanced IC packaging market.

Strategic Analysis: This includes M&A, new product development, and competitive landscape for the advanced IC packaging market.

Analysis of competitive intensity of the industry based on Porter's Five Forces model.

FAQ

Q1. What is the advanced IC packaging market size?

Answer: The global advanced IC packaging market is expected to reach an estimated \$52.3 billion by 2027

Q2. What is the growth forecast for advanced IC packaging market?

Answer: The advanced IC packaging market is expected to grow at a CAGR of 5.7% from 2021 to 2027.

Q3. What are the major drivers influencing the growth of the advanced IC packaging market?

Answer: The major drivers for this market are growing semiconductor industry, increasing miniaturization of electronic devices, demand for higher speed and smaller pitch size, and increasing penetration of 2.5D/3D packaging technology.

Q4. What are the major applications or end use industries for advanced IC packaging?

Answer: Consumer and communication is the major end use industry for advanced IC packaging.

Q5. What are the emerging trends in advanced IC packaging market?

Answer: Emerging trends, which have a direct impact on the dynamics of the industry, include development of packaging solutions for AI and IoT and introduction of new IC packaging technologies, such as fan out and 2.5D/3D.

Q6. Who are the key advanced IC packaging companies?

Answer: Some of the key advanced IC packaging companies are as follows:

Amkor Technology

Taiwan Semiconductor

Advanced Semiconductor Engineering Technology

Intel Corporation

Samsung Electronics

JCET Group

Texas Instruments

Toshiba Corporation

Renesas

Q7. Which advanced IC packaging packaging type segment will be the largest in future?

Answer: Lucintel forecasts that flip-chip will remain the largest segment due to rise in demand for high speed portable devices and high packaging density.

Q8: In advanced IC packaging market, which region is expected to be the largest in next 5 years?

Answer: Asia Pacific is expected to remain the largest region and witness the highest growth over next 5 years

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Answer: Yes, Lucintel provides 10% Customization Without any Additional Cost.

This report answers following 11 key questions

Q.1 What are some of the most promising potential, high growth opportunities for the global advanced IC packaging market by packaging type (flip-chip, fan-in wafer level packaging, embedded-die, fan-out, 2.5D/3D), end use industry (consumer and communication, automotive, industrial, healthcare, aerospace and defense, and others), and region (North America, Europe, Asia Pacific, and the Rest of the World)?

Q. 2 Which segments will grow at a faster pace and why?

Q.3 Which regions will grow at a faster pace and why?

Q.4 What are the key factors affecting market dynamics? What are the drivers and challenges of the market?

Q.5 What are the business risks and threats to the market?

Q.6 What are the emerging trends in this market and the reasons behind them?

Q.7 What are the changing demands of customers in the market?

Q.8 What are the new developments in the market? Which companies are leading these developments?

Q.9 Who are the major players in this market? What strategic initiatives are being implemented by key players for business growth?

Q.10 What are some of the competitive products and processes in this area and how big of a threat do they pose for loss of market share via material or product substitution?

Q.11 What M & A activities have taken place in the last 5 years in this market?

For any questions related to advanced IC packaging market or related to advanced IC packaging companies, advanced IC packaging market share, advanced IC packaging market analysis, advanced IC packaging market size, write Lucintel analyst at email: helpdesk@lucintel.com. We will be glad to get back to you soon.

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